



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# # 20260116001.0
Mold process & Topside marking change for Select devices
Information Only**

Date: January 16, 2026

To: MOUSER PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the Change Management team.

Sincerely,

Change Management Team
SC Business Services

**20260116001.0
Information Only
Attachments**

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TMS320F28075PTPQ	TMS320F28075PTPQ
TMS320F28379DPTPQ	NULL
TMS320F28377DPTPQ	TMS320F28377DPTPQ
TMS320F28075PTPQR	NULL
TMS320F28377SPTPQ	TMS320F28377SPTPQ

Technical details of this Product Change follow on the next page(s).

PCN Number:	20260116001.0			PCN Date:	January 16, 2026									
Title:	Mold process & Topside marking change for Select devices													
Customer Contact:	Change Management team		Dept:	Quality Services										
Proposed 1st Ship Date:	February 15, 2026		Sample requests accepted until:	N/A										
Change Type:														
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Material												
<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Process												
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Fab Site												
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Material												
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Process												
PCN Details														
Description of Change:														
This notice is to communicate an update for the mold process & topside marking change for the devices on the product affected section as follows:														
<table border="1"> <thead> <tr> <th></th> <th>Current</th> <th>Proposed</th> </tr> </thead> <tbody> <tr> <td>Topside marking</td> <td></td> <td></td> </tr> <tr> <td>Mold process</td> <td>With ejector pin Side gate molding</td> <td>Remove ejector pin Center top gate molding</td> </tr> </tbody> </table>							Current	Proposed	Topside marking			Mold process	With ejector pin Side gate molding	Remove ejector pin Center top gate molding
	Current	Proposed												
Topside marking														
Mold process	With ejector pin Side gate molding	Remove ejector pin Center top gate molding												
Reason for Change:														
Continuity of Supply														
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):														
None														
Impact on Environmental Ratings:														
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.														
<input checked="" type="checkbox"/> RoHS <input checked="" type="checkbox"/> No Change		<input checked="" type="checkbox"/> REACH <input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> Green Status <input checked="" type="checkbox"/> No Change	IEC 62474 <input checked="" type="checkbox"/> No Change										
Changes to product identification resulting from this PCN:														
None														
Product Affected:														
TMS320F28075PTPQ	TMS320F28377DPTPQ	TMS320F28379DPTPQ												
TMS320F28075PTPQR	TMS320F28377SPTPQ													

Qualification Data
Automotive Qualification Summary
(As per AEC-Q100 Rev. J and JEDEC Guidelines)
 Approve Date 26-November-2024

Product Attributes

Attributes		Qual Device: TMS320F28377DPTPQ
Automotive Grade Level		Grade 1
Operating Temp Range (C)		-40 to 125
Product Function		Microprocessor
Wafer Fab Supplier		TSMC-F14
Assembly Site		PHI
Package Group		QFP
Package Designator		PTP
Pin Count		176

QBS: Qual By Similarity, also known as Generic Data
 Qual Device TMS320F28377DPTPQ is qualified at MSL3 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: TMS320F28377DPTPQ
Test Group A - Accelerated Environment Stress Tests								
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL3 260C	-	3/231/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	3/231/0
Test Group B - Accelerated Lifetime Simulation Tests								
Test Group C - Package Assembly Integrity Tests								
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	3/30/0
Test Group D - Die Fabrication Reliability Tests								
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests								
Additional Tests								

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2403-083

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

ZVEI ID: SEM-PA-13, SEM-PA-21

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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